ASM NEXX equipment processes the fastest growing, highest technology interconnects in the advanced packaging market

ASM NEXX, Inc. is a systems engineering integration company in a micro-scale environment

ASM NEXX, Inc. brings together hardware and software to process metals under the highest specifications at the micron scale

ASM NEXX equipment processes wafers, panels and other substrates for semiconductor manufacturing leaders 24-hours a day, 7-days a week, 365-days a year

Growth rate forecasts for 2017 - 2022 for interconnects by technology in 300 mm equivalent wafer starts

Serving our customers in Asia, Europe and North America for over 15 years

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PVD Wafer
Apollo

ECD Wafer
Stratus™

ECD Panel
Stratus™

For wafers, panels & more
**Physical Vapor Deposition**

**Apollo**  
Wafer Level

- Highest flexibility sputtering tool on the market in the smallest footprint
- Bridge capability for 100, 150, 200 & 300 mm wafers as well as package level
- Configurable for up to 5 metal targets
- Safe wafer handling for various fragile substrates, thin and bowed wafer types

**More flexible features**

**Stratus™**  
Wafer Level

- Highest flexibility plating tool on the market
- Bridge capability for 100, 150 & 200 mm or 200 & 300 mm wafers
- Processes up to 6 chemistries at one time
- Safe wafer handling for various fragile substrates, thin and bowed wafer types

**Safer substrate handling**

**Stratus™**  
Panel Level

- Highest wafer scale precision solution on the market for panels
- Handles panel sizes up to 510 x 515 mm
- Processes up to 5 chemistries at one time
- Safe wafer handling for various fragile substrates, thin and bowed wafer types

**Higher precision technology**

**With more applications ...**

- Under bump metallization for bumping and redistribution layers
- Interposers, fan out and TSV
- RF Filter wafer level chip scale processing
- Power Devices (FSM & BSM)

**The right choice for you and your customers**

- Wafer bumping (RDL, Cu Pillar, Microbump and Au)
- Interposers, fan out and TSV
- RF Filter wafer level chip scale processing
- Power Devices (FSM & BSM)

- Fan out panel scale plating
- Embedded interconnections in substrate